IRHNME9A7024 (JANSR2N7650U8CE)

PD-98030

Radiation Hardened Power MOSFET
Surface Mount (SMD-0.2e Ceramic Lid)
60V, 25A, N-channel, R9 Superjunction Technology

Features

- Single event effect (SEE) hardened (up to LET of 90 MeV·cm^2/mg)
- Low $R_{DS(on)}$
- Fast switching
- Low total gate charge
- Simple drive requirements
- Hermetically sealed
- Ceramic package
- Light weight
- Surface mount
- ESD rating: Class 1C per MIL-STD-750, Method 1020

Product Summary

- **BV_{DSS}:** 60V
- **I_D:** 25A*
- **$R_{DS(on),max}$:** 30mΩ
- **Q_{Gmax}:** 31nC
- **REF:** MIL-PRF-19500/776

SMD-0.2e (Ceramic Lid)

Potential Applications

- Isolated DC-DC converter
- Motor drives
- Point-of-Load (PoL) converter

Product Validation

Qualified to JANS screening flow according to MIL-PRF-19500 for space applications

Description

IR HiRel R9 technology provides superior power MOSFETs for space applications. These devices have improved immunity to Single Event Effect (SEE) and have been characterized for useful performance with Linear Energy Transfer (LET) up to 90 MeV·cm^2/mg. Their combination of low $R_{DS(on)}$ and fast switching times will allow for better performance in applications such as DC-DC converter or motor drives. These devices retain all of the well-established advantages of MOSFETs such as voltage control, fast switching and temperature stability of electrical parameters.

Ordering Information

Table 1 Ordering options

Part number	Package	Screening Level	TID Level
IRHNME9A7024	SMD-0.2e (Ceramic Lid)	COTS	100 krad(Si)
JANSR2N7650U8CE	SMD-0.2e (Ceramic Lid)	JANS	100 krad(Si)
IRHNME9A3024	SMD-0.2e (Ceramic Lid)	COTS	300 krad(Si)
JANSF2N7650U8CE	SMD-0.2e (Ceramic Lid)	JANS	300 krad(Si)

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1 Absolute Maximum Ratings

Table 2 Absolute Maximum Ratings (Pre-Irradiation)

Symbol	Parameter	Value	Unit
I_{D1} @ V_{GS} = 12V, T_C = 25°C	Continuous Drain Current	25*	A
I_{D2} @ V_{GS} = 12V, T_C = 100°C	Continuous Drain Current	20	A
I_{DM} @ T_C = 25°C	Pulsed Drain Current [1]	100	A
P_D @ T_C = 25°C	Maximum Power Dissipation	54	W
	Linear Derating Factor	0.43	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy [2]	520	mJ
I_{AR}	Avalanche Current [1]	25	A
E_{AR}	Repetitive Avalanche Energy [1]	5.4	mJ
dv/dt	Peak Diode Reverse Recovery [3]	8.6	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C
	Lead Temperature	300 (for 5s)	
	Weight	0.25 (Typical)	g

*Current is limited by package

[1] Repetitive Rating; Pulse width limited by maximum junction temperature.

[2] V_{DD} = 60V, starting T_J = 25°C, L = 2.6mH, Peak I_L = 20A, V_{GS} = 20V

[3] $I_{SD} \leq$ 25A, di/dt $\leq$ 1300A/µs, $V_{DD} \leq$ 60V, $T_J \leq$ 150°C

2 Device Characteristics

2.1 Electrical Characteristics (Pre-Irradiation)

Table 3 Static and Dynamic Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	60	—	—	V	V_{GS} = 0V, I_D = 1.0mA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.06	—	V/°C	Reference to 25°C, I_D = 1.0mA
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	30	mΩ	V_{GS} = 12V, I_{D2} = 20A [1]
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	V_{DS} = V_{GS}, I_D = 650µA
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-7.2	—	mV/°C	
Gfs	Forward Transconductance	10	—	—	S	V_{DS} = 15V, I_{D2} = 20A [1]
I_{DSS}	Zero Gate Voltage Drain Current	—	—	1.0	µA	V_{DS} = 48V, V_{GS} = 0V
		—	—	10		V_{DS} = 48V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V_{GS} = 20V
	Gate-to-Source Leakage Reverse	—	—	-100		V_{GS} = -20V
Q_G	Total Gate Charge	—	—	31	nC	I_{D1} = 25A V_{DS} = 30V V_{GS} = 12V
Q_{GS}	Gate-to-Source Charge	—	—	10		
Q_{GD}	Gate-to-Drain ('Miller') Charge	—	—	6.4		
$t_{d(on)}$	Turn-On Delay Time	—	—	11	ns	I_{D1} = 25A ** V_{DD} = 30V R_G = 7.5Ω V_{GS} = 12V
t_r	Rise Time	—	—	20		
$t_{d(off)}$	Turn-Off Delay Time	—	—	29		
t_f	Fall Time	—	—	12		
$L_s + L_D$	Total Inductance	—	6.8	—	nH	Measured from center of Drain pad to center of Source pad
C_{iss}	Input Capacitance	—	1160	—	pF	V_{GS} = 0V V_{DS} = 25V f = 1.0MHz
C_{oss}	Output Capacitance	—	440	—		
C_{rss}	Reverse Transfer Capacitance	—	2.6	—		
R_G	Gate Resistance	—	1.5	—	Ω	f = 1.0MHz, open drain

** Switching speed maximum limits are based on manufacturing test equipment and capability.

[1] Pulse width ≤ 300 µs; Duty Cycle ≤ 2%

2.2 Source-Drain Diode Ratings and Characteristics (Pre-Irradiation)

Table 4 Source-Drain Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	25	A	
I_{SM}	Pulsed Source Current (Body Diode) [1]	—	—	100	A	
V_{SD}	Diode Forward Voltage	—	—	1.2	V	T_J = 25°C, I_S = 25A, V_{GS} = 0V [2]
t_{rr}	Reverse Recovery Time	—	75	150	ns	T_J = 25°C, I_F = 25A, V_{DD} ≤ 25V di/dt = 100A/µs [2]
Q_{rr}	Reverse Recovery Charge	—	250	—	nC	
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

2.3 Thermal Characteristics

Table 5 Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction-to-Case	—	—	2.3	°C/W

2.4 Radiation Characteristics

IR HiRel radiation hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at IR HiRel is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 3 and 4) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

2.4.1 Electrical Characteristics — Post Total Dose Irradiation

Table 6 Electrical Characteristics @ T_j = 25°C, Post Total Dose Irradiation [3, 4]

Symbol	Parameter	Up to 300 krads (Si)[5]		Unit	Test Conditions
		Min.	Max.		
BV_{DSS}	Drain-to-Source Breakdown Voltage	60	—	V	V_{GS} = 0V, I_D = 1mA
$V_{GS(th)}$	Gate Threshold Voltage	2.0	4.0	V	V_{DS} = V_{GS}, I_D = 650µA
I_{GSS}	Gate-to-Source Leakage Forward	—	100	nA	V_{GS} = 20V
	Gate-to-Source Leakage Reverse	—	-100		V_{GS} = -20V
I_{DSS}	Zero Gate Voltage Drain Current	—	1.0	µA	V_{DS} = 48V, V_{GS} = 0V
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance (TO-3) [2]	—	30	mΩ	V_{GS} = 12V, I_{D2} = 20A
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance (SMD-0.2) [2]	—	30	mΩ	V_{GS} = 12V, I_{D2} = 20A
V_{SD}	Diode Forward Voltage	—	1.2	V	V_{GS} = 0V, I_F = 25A

[1] Repetitive Rating; Pulse width limited by maximum junction temperature.
[2] Pulse width ≤ 300 µs; Duty Cycle ≤ 2%
[3] Total Dose Irradiation with V_{GS} Bias. V_{GS} =-12V applied and V_{DS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.
[4] Total Dose Irradiation with V_{DS} Bias. V_{DS} = 48V applied and V_{GS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.
[5] Part numbers IRHNME9A7024 (JANSR2N7650U8CE) and IRHNME9A3024 (JANSF2N7650U8CE).

2.4.2 Single Event Effects — Safe Operating Area

IR HiRel radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. 1 and Table 7.

Table 7 Typical Single Event Effects Safe Operating Area

LET (MeV·cm²/mg)	Energy (MeV)	Range (µm)	V_{DS} (V)			
			V_{GS} = 0V	V_{GS} = -1V	V_{GS} =- 5V	V_{GS} = -10V
38 ± 5%	355 ± 7.5%	43 ± 7.5%	60	60	60	60
60 ± 5%	753 ± 7.5%	60 ± 10%	60	60	60	60
90 ± 5%	1515 ± 7.5%	82 ± 7.5%	60	60	—	—

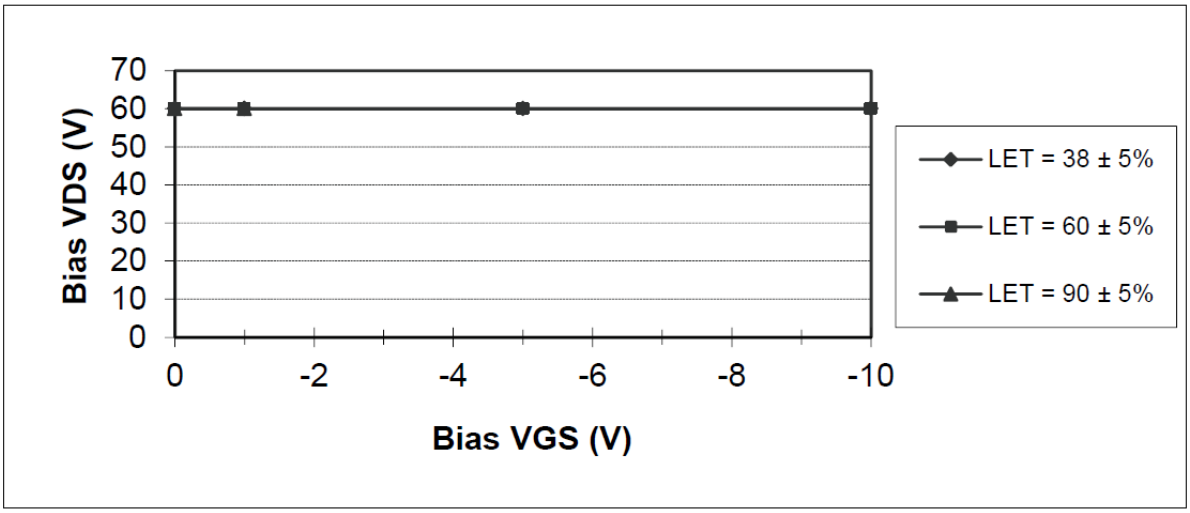


Figure 1 Typical Single Event Effect, Safe Operating Area

3 Electrical Characteristics Curves (Pre-irradiation)

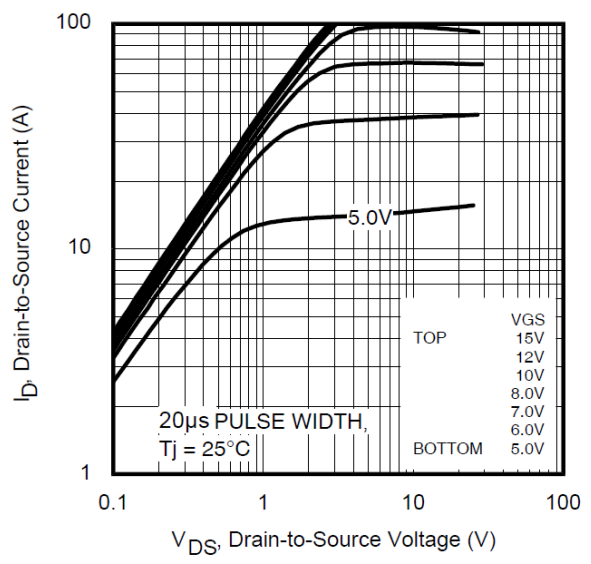


Figure 2 **Typical Output Characteristics**

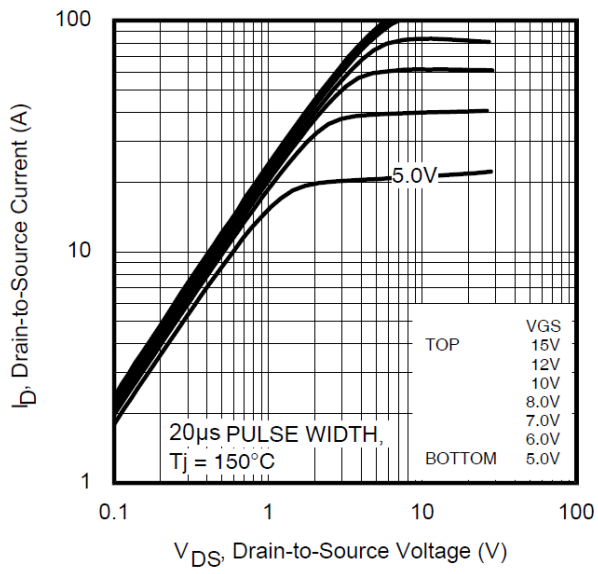


Figure 3 **Typical Output Characteristics**

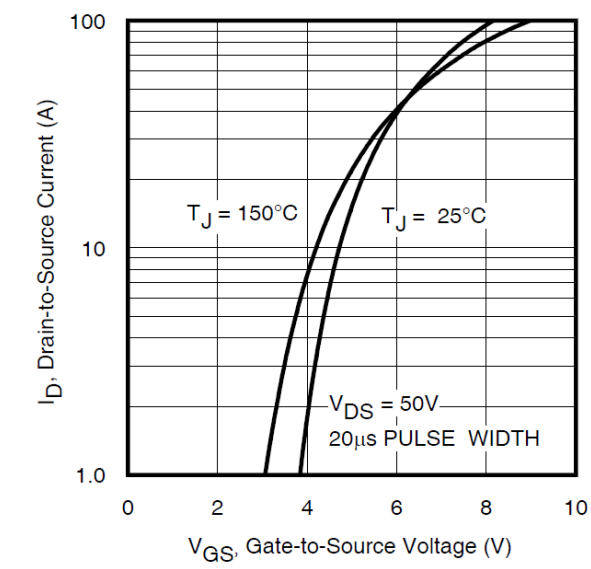


Figure 4 **Typical Transfer Characteristics**

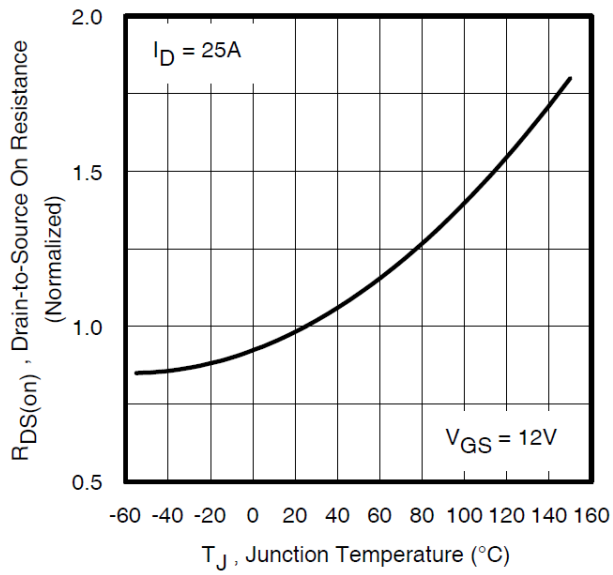


Figure 5 **Normalized On-Resistance Vs. Temperature**

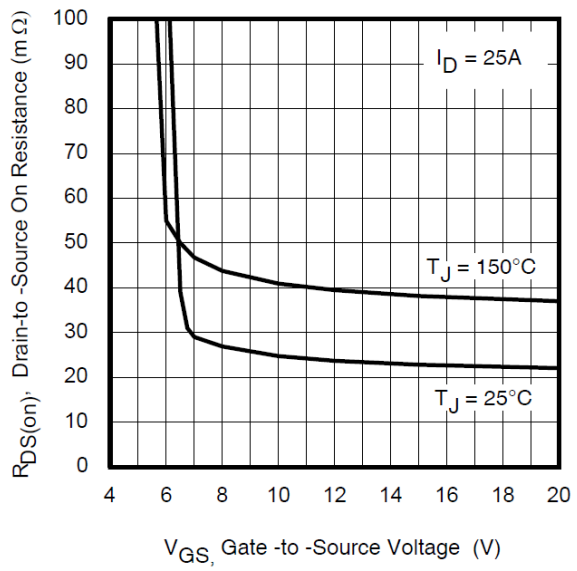


Figure 6 **Typical On-Resistance Vs. Gate Voltage**

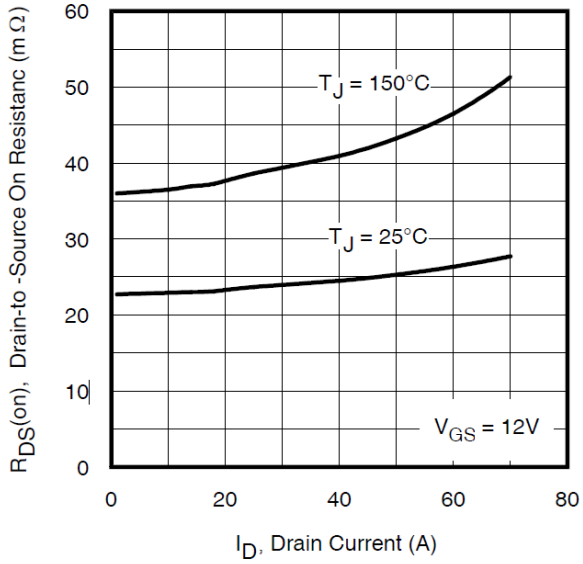


Figure 7 **Typical On-Resistance Vs. Drain Current**

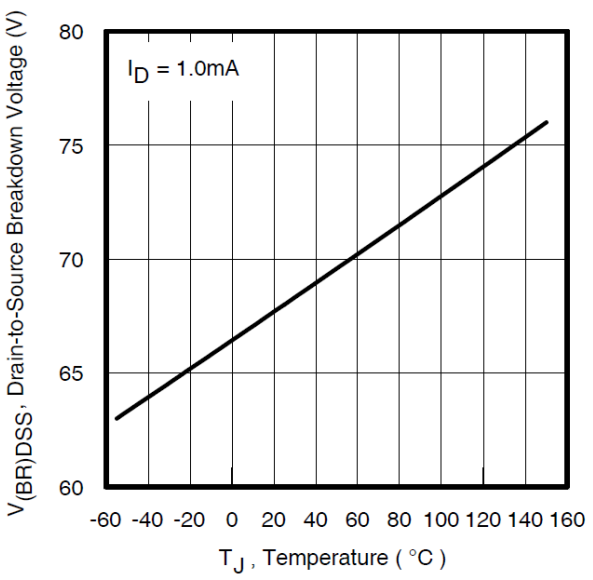


Figure 8 **Typical Drain-to-Source Breakdown Voltage Vs. Temperature**

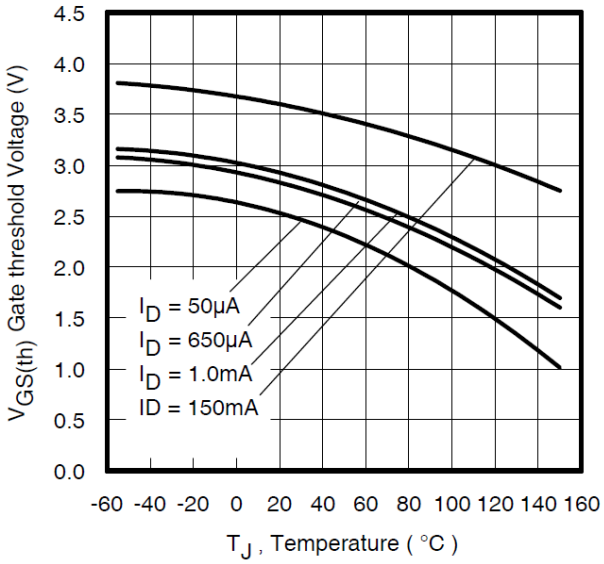


Figure 9 **Typical Threshold Voltage Vs. Temperature**

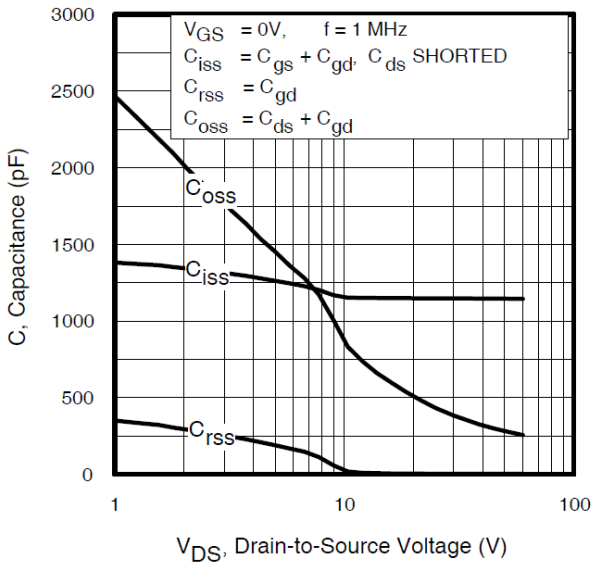


Figure 10 **Typical Capacitance Vs. Drain-to-Source Voltage**

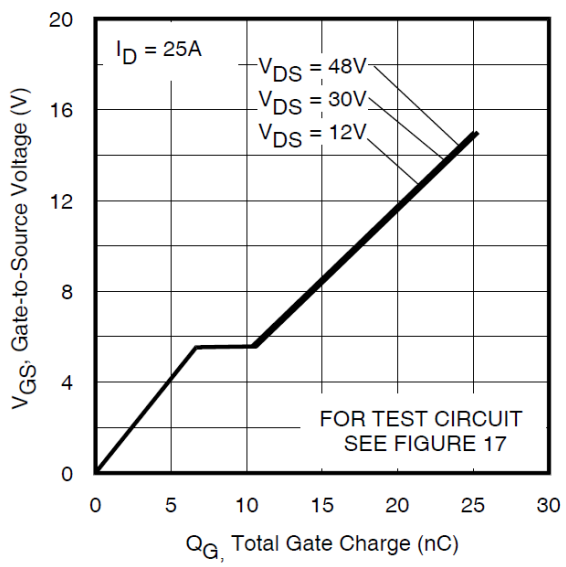


Figure 11 **Typical Gate Charge Vs. Gate-to-Source Voltage**

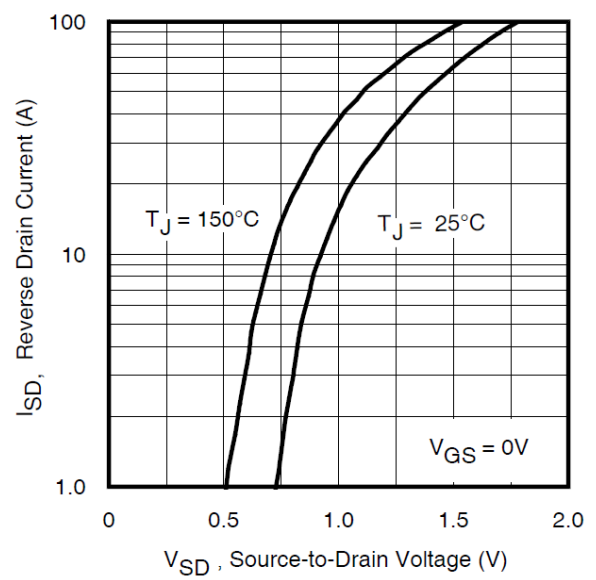


Figure 12 **Typical Source-Drain Vs. Diode Forward Voltage**

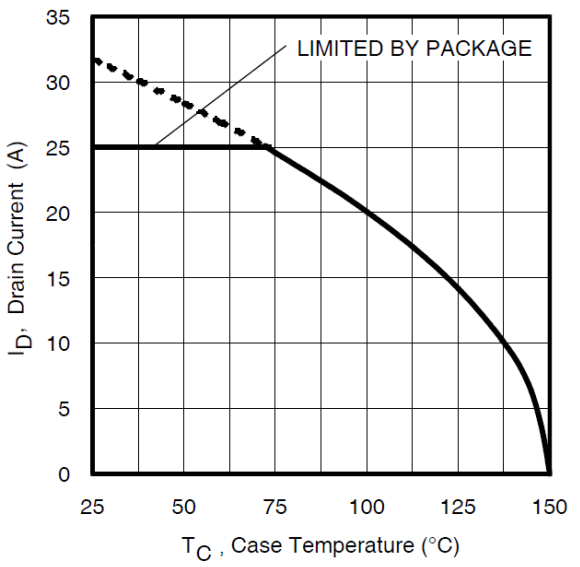


Figure 13 **Maximum Drain Current Vs. Case Temperature**

Electrical Characteristics Curves (Pre-irradiation)

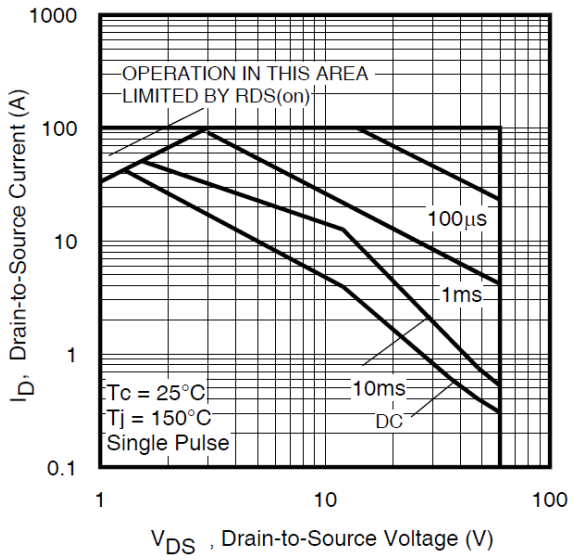


Figure 14 Maximum Safe Operating Area

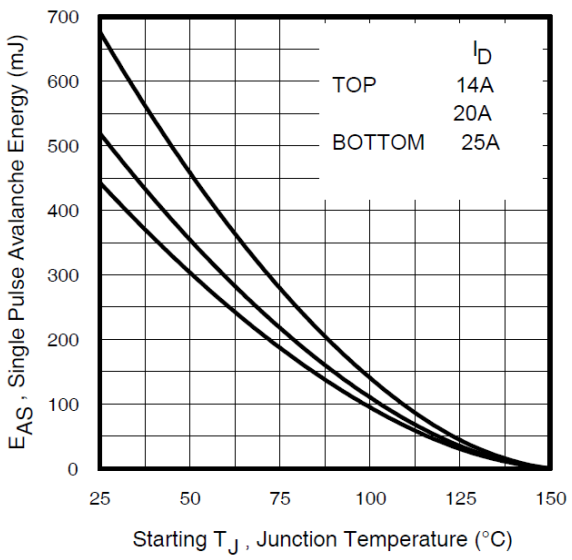


Figure 15 Maximum Effective Transient Thermal Impedance, Junction-to-Case

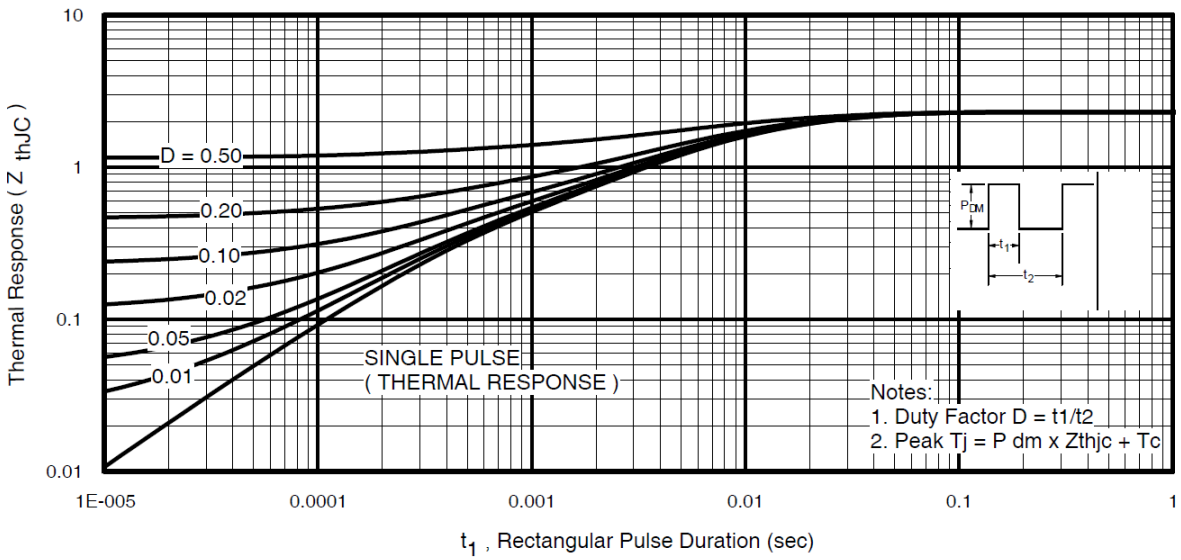
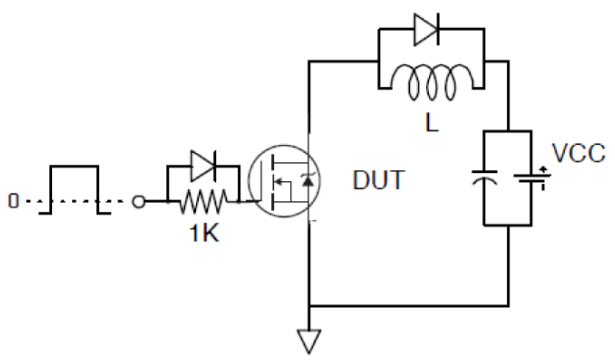


Figure 16 Maximum Effective Transient Thermal Impedance, Junction-to-Case

4 Test Circuits (Pre-irradiation)



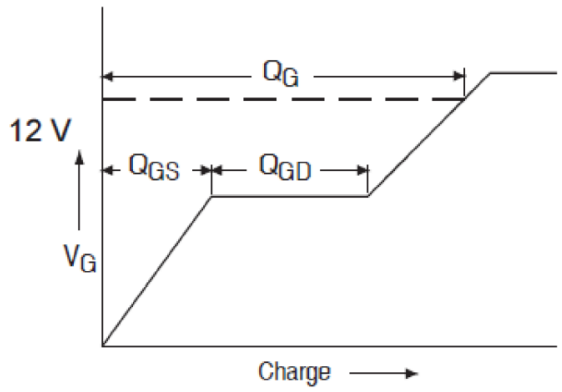
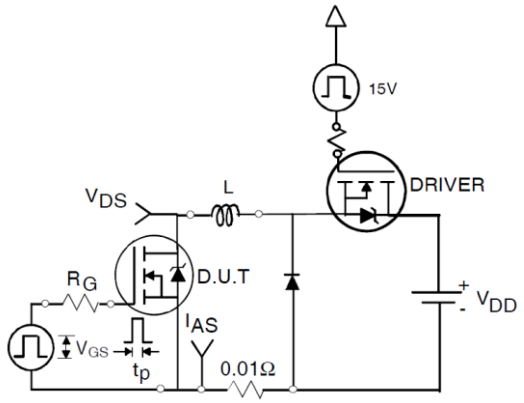


Figure 17 Gate Charge Test Circuit

Figure 18 Gate Charge Waveform



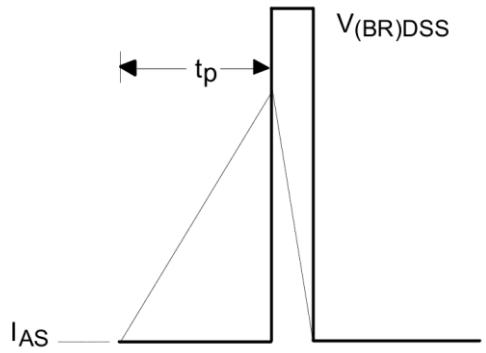
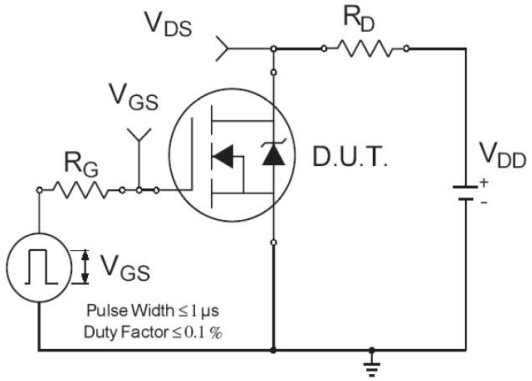


Figure 19 Unclamped Inductive Test Circuit

Figure 20 Unclamped Inductive Waveform



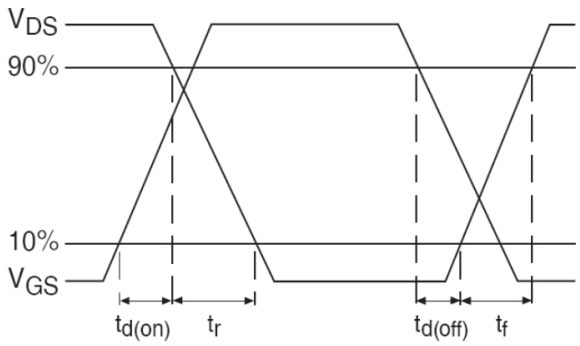


Figure 21 Switching Time Test Circuit

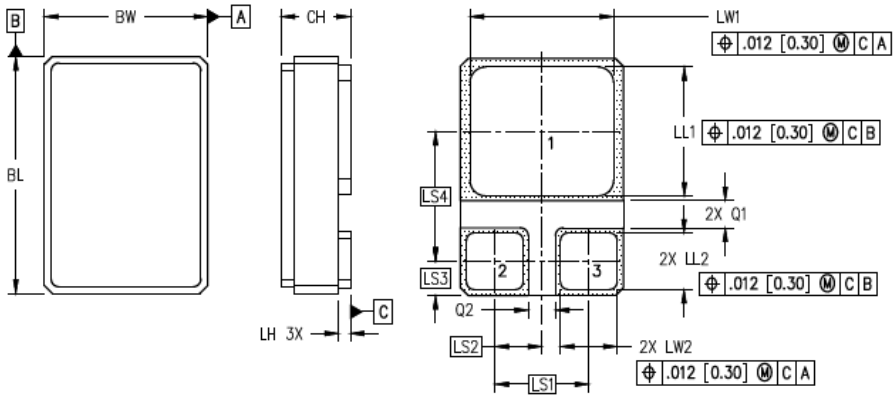
Figure 22 Switching Time Waveforms

5 Package Outline

Note: For the most updated package outline, please see the website: [SMD-0.2e (Ceramic Lid)]

PART NO. D101029G

REV.	DESCRIPTION	ECN	DATE
B	CHANGE PER ECN	Z8F80853555	10–8–25



DIMENSIONS						
	INCHES			MILLIMETERS		
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
BL	.300	.305	.310	7.62	7.75	7.87
BW	.205	.210	.215	5.21	5.33	5.46
CH			.097			2.46
LH	.010	.015	.020	0.25	0.38	0.51
LW1	.180	.185	.190	4.57	4.70	4.83
LW2	.068	.073	.078	1.73	1.85	1.98
LL1	.161	.166	.171	4.09	4.22	4.34
LL2	.068	.073	.078	1.73	1.85	1.98
LS1	.121 BSC			3.07 BSC		
LS2	.061 BSC			1.55 BSC		
LS3	.044 BSC			1.12 BSC		
LS4	.167 BSC			4.24 BSC		
Q1	.030			0.76		
Q2	.030			0.76		
N	3			3		

PAD ASSIGMENTS
1 = DRAIN
2 = GATE
3 = SOURCE

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M.
2. CONTROLLING DIMENSION: INCHES
3. FEATURE CONTROL FRAME TOLERANCE SHOWN IN INCHES [MILLIMETERS].
4. SYMBOL N IS MAXIMUM NUMBER OF TERMINALS.
5. LEAD PLATING IS GOLD. STANDARD FINAL LEAD FINISH IS SOLDER ALLOY 63Sn/37Pb. DIMENSIONS APPLY BEFORE SOLDER FINISH.

Approvals	Name	Signature	Date
Drawn By	K. Toto	[illegible]	10–8–25

APPROVALS ON FILE

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IR HiRel
An Infineon Technologies Company
205 Crawford Street
Leominster, Ma. 01453

CODE ID 69210 | A

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE:
XXX = ± .005
XX = ± .01
ANGLES = ± .5°

TITLE: SMD–0.2 ENHANCED OUTLINE WITH CERAMIC LID

DRAWING NO. D101029G | REV. B

SCALE NONE | SHT. 1 OF 1

Revision history

Document version	Date of release	Description of changes
	10/03/2025	Final datasheet with PD number (PD-98030)

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WARNINGS

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest International Rectifier HiRel Products, Inc., an Infineon Technologies company, office.

International Rectifier HiRel Components may only be used in life-support devices or systems with the expressed written approval of International Rectifier HiRel Products, Inc., an Infineon Technologies company, if failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety and effectiveness of that device or system.

Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.